

PATENT APPLICATION  
IN THE U.S. PATENT AND TRADEMARK OFFICE

June 13, 2002

Applicant(s): Chikao IKENAGA, et al.  
For : FRAME FOR SEMICONDUCTOR PACKAGE

Serial No. : 09/850 213

Group: 2826

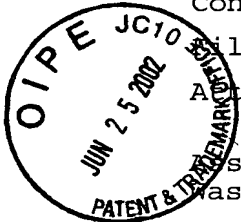
Confirmation No.: 9610

Filed : May 7, 2001

Examiner: Greene

App. Docket No.: OPS C-533

Assistant Commissioner for Patents  
Washington, DC 20231



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PETITION FOR TIME EXTENSION, AND CERTIFICATE OF MAILING

Sir:

A Response is enclosed.

Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by one month(s). The extension fee is:

☒ \$110.00 (37 CFR 1.17)

☐ \$ (37 CFR 1.17; small entity status established by verified statement(s) submitted previously).

A check for \$374.00 is enclosed to cover fees.

If this Petition is not timely received, please extend the shortened period an additional month. Please credit any over-payment, or charge any additional fee required by this Petition, to Deposit Account No. 06-1382. A duplicate of this Petition is enclosed.

Respectfully submitted,

IN DUPLICATE

LLC/ad

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*[Signature]*  
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Reg. No. 32 549  
Reg. No. 36 589  
Reg. No. 31 257  
Reg. No. 24 949  
Reg. No. 40 694  
Reg. No. 36 328  
Reg. No. 44 621

Encl: Check  
Response dated June 13, 2002

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231 on June 17, 2002.

180.0112

*[Signature]*  
Liane L. Churney